



Description

The 6N137S consists of an infrared emitting diode optically coupled to a high speed integrated photo detector logic gate with a strobable output. It is packaged in a 8-pin DIP package and available in wide-lead spacing and SMD options.

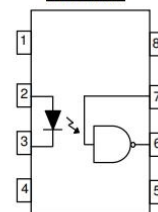
Features

- High speed 10Mbit/s
- 10kV/ μ s min. common mode transient immunity
- Guaranteed performance from -40 to 85°C
- Logic gate output
- High isolation voltage between input and output (Viso=5000 V rms)
- Pb free and RoHS compliant.
- CQC approved
- UL approved
- VDE approved



Pin 1

Schematic



A 0.1 μ F bypass capacitor must be connected between pins 8 and 5⁻³

Pin Configuration

- 1, No Connection
- 2, Anode
- 3, Cathode
- 4, No Connection
- 5, Gnd
- 6, Vout
- 7, VE
- 8, VCC

Applications

- Ground loop elimination
- LSTTL to TTL, LSTTL or 5 volt CMOS
- Line receiver, data transmission
- Data multiplexing
- Switching power supplies
- Pulse transformer replacement
- Computer peripheral interface
- High speed logic ground isolation

Truth Table (Positive Logic)

Input	Enable	Output
H	H	L
L	H	H
H	L	H
L	L	H
H	NC	L
L	NC	H



Maximum Ratings(Ta=25°C)

Parameter		Symbol	Values	Unit
Input	Forward Current	I _F	50	mA
	Enable input voltage Not exceed VCC by more than 500mV	V _E	5.5	V
	Reverse voltage	V _R	5	V
	Power dissipation	P _D	100	mW
Output	Power dissipation	P _C	85	mW
	Output current	V _{ECO}	50	mA
	Output voltage	V _O	7.0	V
	Supply voltage	V _{CC}	7.0	V
Output Power Dissipation		P _O	100	mW
Isolation voltage ⁽¹⁾		V _{ISO}	5000	V rms
Operating temperature		T _{OPR}	-40 ~ +85	°C
Storage temperature		T _{STG}	-55 ~ +125	°C
Soldering temperature ⁽²⁾		T _{SOL}	260	°C

Notes:

(1). AC for 1 minute, R.H.= 40 ~ 60% R.H. In this test, pins 1, 2, 3 & 4 are shorted together, and pins 5, 6, 7 & 8 are shorted together.

(2).For 10 seconds

Electronic Optical Characteristics (TA = -40 to 85°C unless specified otherwise)

Parameter		Symbol	Min.	Typ.	Max.	Unit	Conditon
Input	Forward Voltage	V _F	-	1.4	1.8	V	I _F =10mA
	Reverse voltage	V _R	5.0	-	-	V	I _R =10μA
	Temperature coefficient of forward voltage	ΔV _F /ΔT _A	-	-1.8	-	mV/°C	I _F =10mA
	Input capacitance	C _{IN}	-	60	-	pF	V _F =0, f=1MHz
Output	High level supply current	I _{CC} H	-	7	10	mA	I _F =0mA, V _E =0.5V, V _{CC} =5.5V
	Low level supply current	I _{CC} L	-	9	13	mA	I _F =10mA, V _{CC} =5.5V
	High level enable current ⁽³⁾	I _{EH}	-	-0.6	-1.6	mA	V _E =2.0 V, V _{CC} =5.5V
	Low level enable current ⁽³⁾	I _{EL}	-	-0.8	-1.6	mA	V _E =0.5 V, V _{CC} =5.5V
	High level enable voltage ⁽³⁾	V _{EH}	2.0	-	-	V	I _F =10mA, V _{CC} =5.5V
	Low level enable voltage ⁽³⁾⁽⁴⁾	V _{EL}	-	-	0.8	V	I _F =10mA, V _{CC} =5.5V



Transfer Characteristics (Ta=-40 to 85°C unless specified otherwise)

Parameter	Symbol	Min.	Typ.	Max.	Unit	Conditon
HIGH Level Output Current	I _{OH}	-	2.1	100	uA	V _{CC} =5.5V, V _O =5.5V, I _F =250μA, V _E =2.0V
LOW Level Output Current	V _{OL}	-	0.35	0.6	V	V _{CC} = 5.5V, I _F =5mA, V _E =2.0V, I _{CL} =13mA
Input Threshold Current	I _{FT}	-	2.5	5	mA	V _{CC} = 5.5V, V _O =0.6V, V _E =2.0V, I _{OL} =13mA

Switching Characteristics

(Ta=-40 to 85°C, VCC=5V, IF=7.5mA unless specified otherwise)

Parameter	Symbol	Min.	Typ.	Max.	Unit	Conditon
Propagation delay time to output High level ⁽⁵⁾ (Fig.12)	T _{PHL}	-	35	75	ns	C _L = 15pF, R _L =350Ω, T _A =25°C
Propagation delay time to output Low level ⁽⁶⁾ (Fig.12)	T _{PLH}	-	40	75	ns	C _L = 15pF, R _L =350Ω, T _A =25°C
Pulse width distortion	T _{phl} – T _{plh}	-	5	35	ns	C _L = 15pF, R _L =350Ω
Output rise time ⁽⁷⁾ (Fig.12)	t _r	-	40	-	ns	C _L = 15pF, R _L =350Ω
Output fall time ⁽⁸⁾ (Fig.12)	t _f	-	10	-	ns	C _L = 15pF, R _L =350Ω
Enable Propagation Delay Time to Output High Level ⁽⁹⁾ (Fig.13)	t _{ELH}	-	15	-	ns	I _F = 7.5mA , V _{EH} =3.5V, C _L =15pF, R _L =350Ω
Enable Propagation Delay Time to Output Low Level ⁽¹⁰⁾ (Fig.13)	t _{EHL}	-	15	-	ns	I _F = 7.5mA , V _{EH} =3.5V, C _L =15pF, R _L =350Ω



Typical Electro-Optical Characteristics Curves

Fig.1 Input Diode Forward Voltage vs. Forward Current

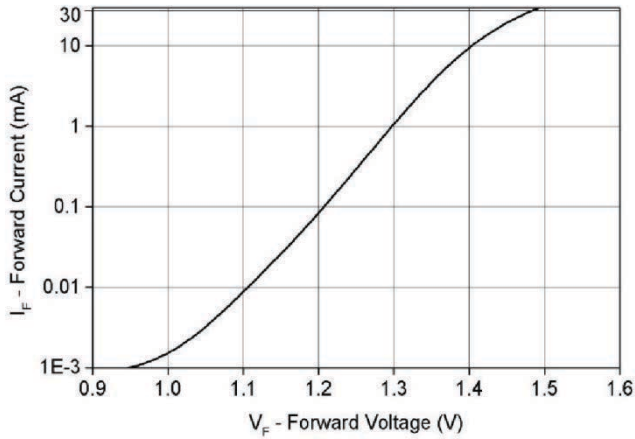


Fig.2 Low Level Output Voltage vs. Ambient Temperature

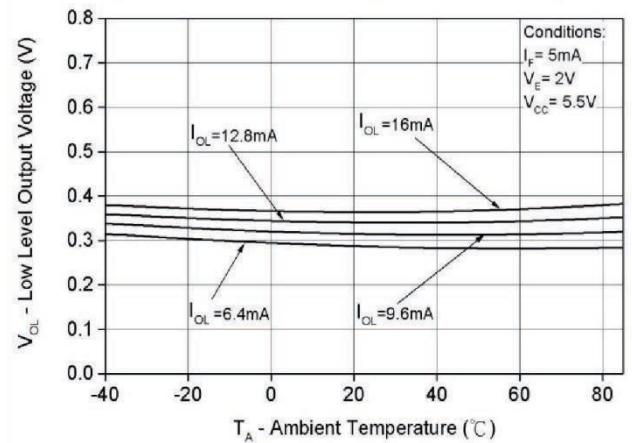


Fig.3 Low Level Output Current vs. Ambient Temperature

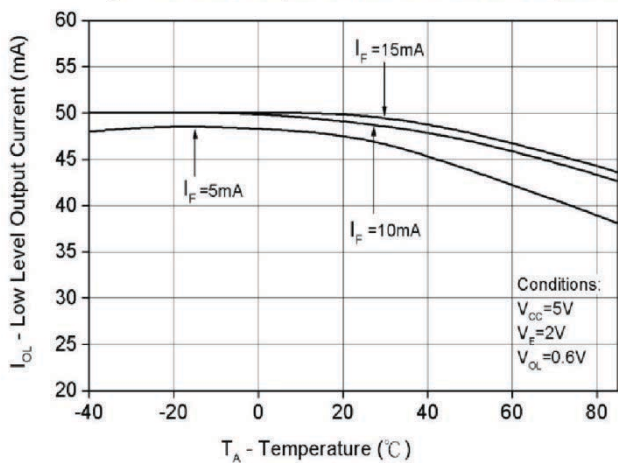


Fig.4 Input Threshold Current vs. Ambient Temperature

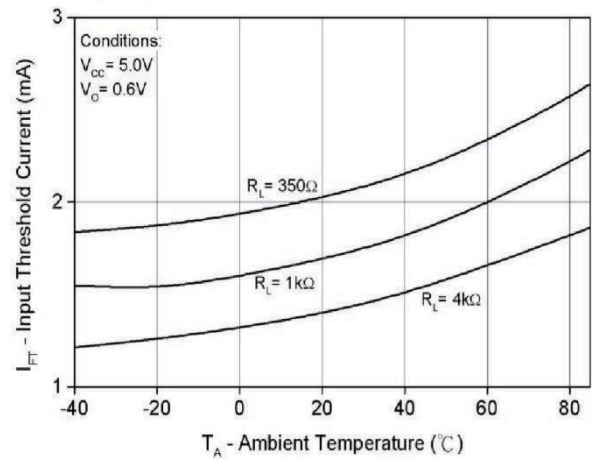


Fig.5 Output Voltage vs. Input Forward Current

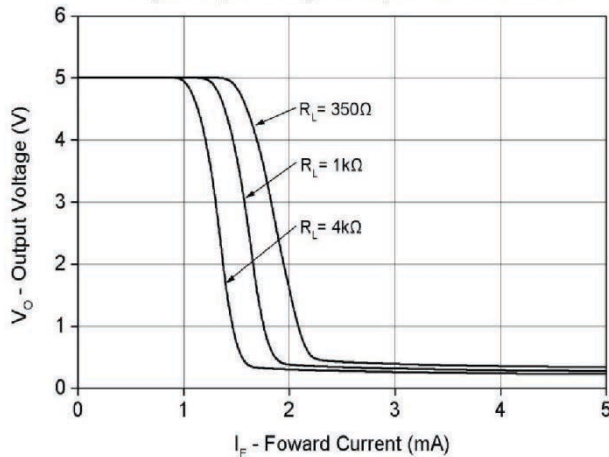


Fig.6 High Level Output Current vs. Temperature

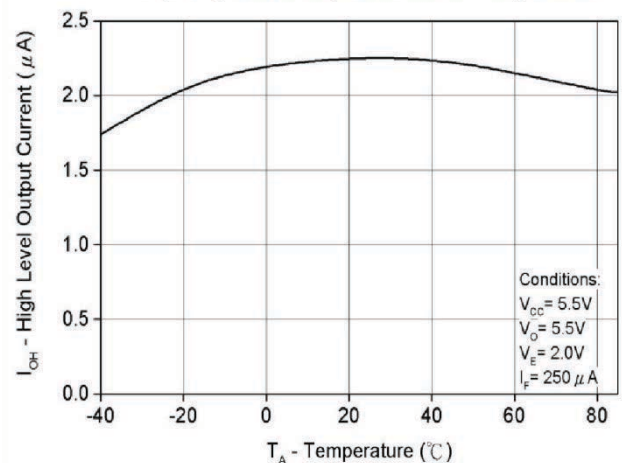




Fig.7 Switching Time vs. Forward Current

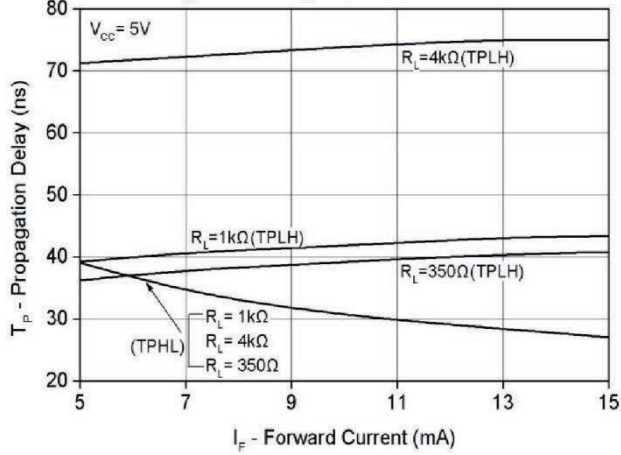


Fig.8 Switching Time vs. Temperature

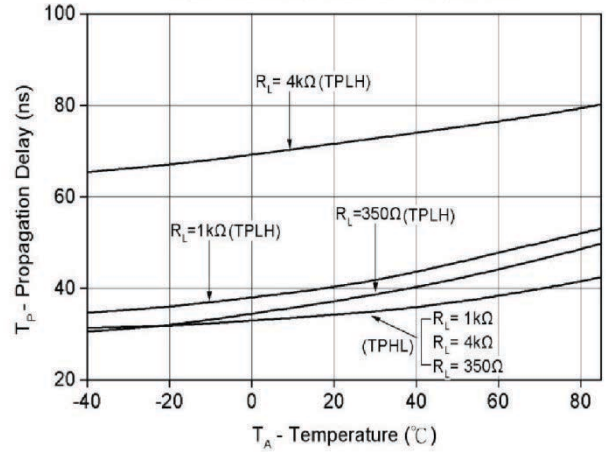


Fig.9 Pulse Width Distortion vs. Temperature

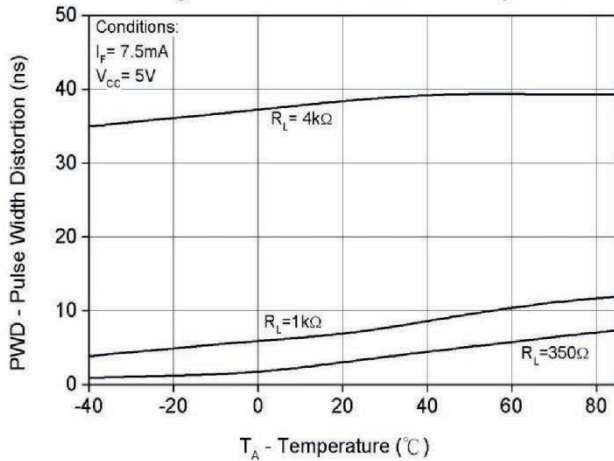


Fig.10 Rise and Fall Time vs. Temperature

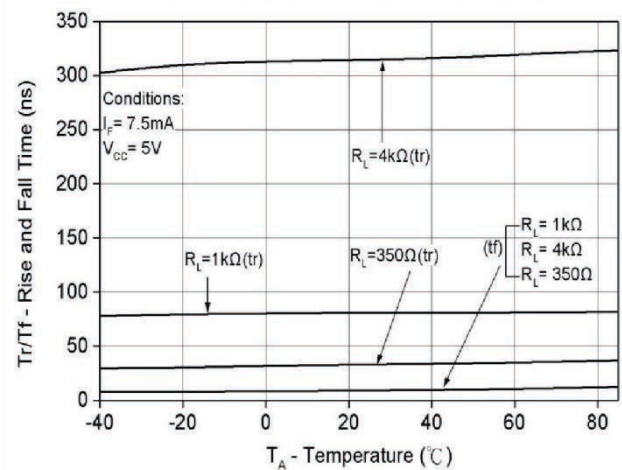


Fig.11 Enable Propagation Delay vs. Temperature

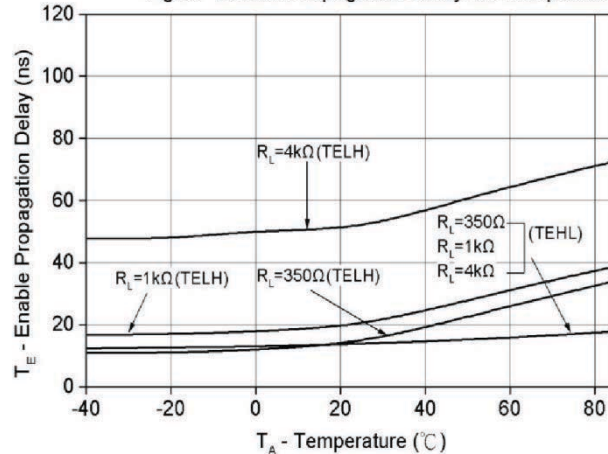




Fig. 12 Test circuit and waveforms for t_{PHL} , t_{PLH} , t_r , and t_f

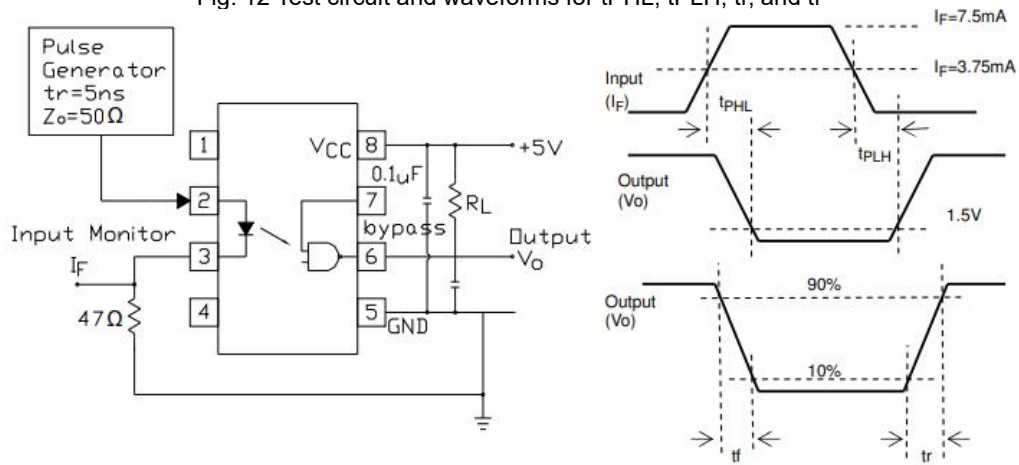


Fig. 13 Test circuit and waveform for t_{EHL} and t_{ELH}

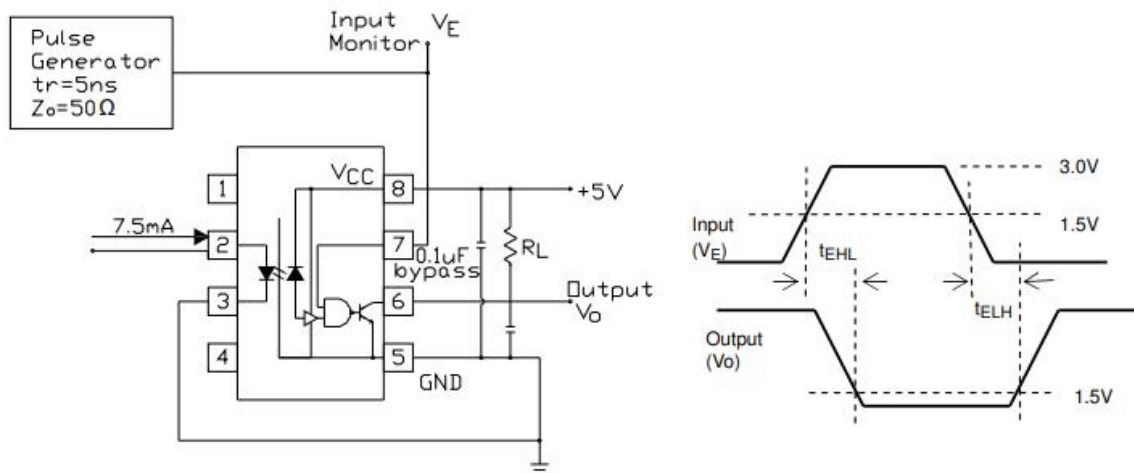
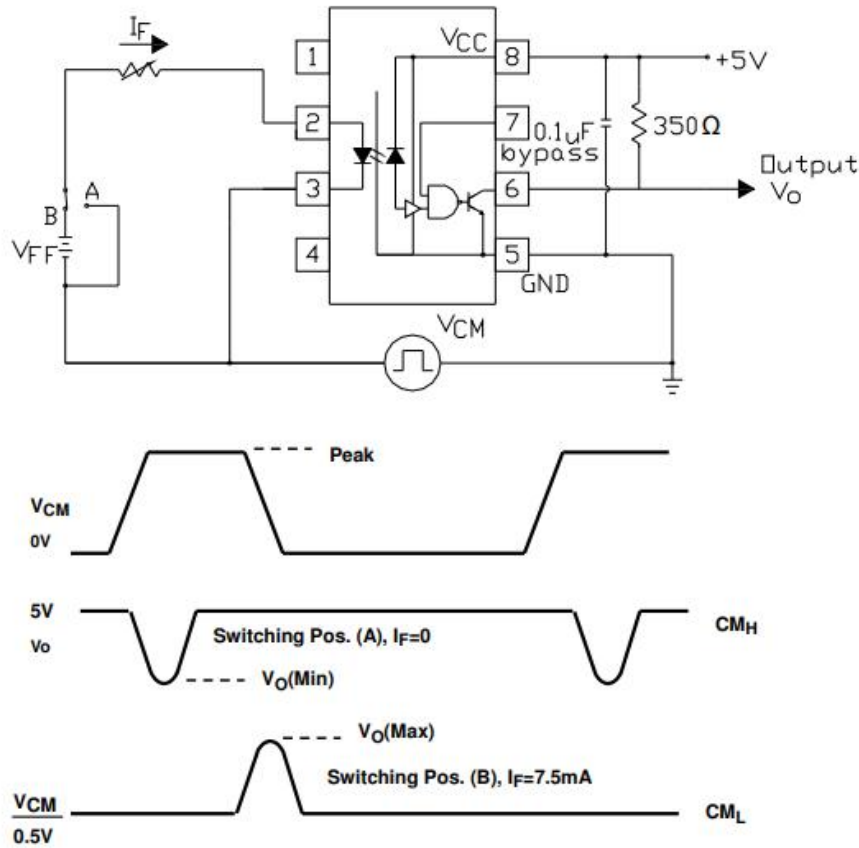




Fig. 14 Test circuit Common mode Transient



Note

(3) The VCC supply must be bypassed by a 0.1μF capacitor or larger. This can be either a ceramic or solid tantalum capacitor with good high frequency characteristic and should be connected as close as possible to the package VCC and GND pins

(4) Enable Input – No pull up resistor required as the device has an internal pull up resistor.

(5) tPLH– Propagation delay is measured from the 3.75mA level on the HIGH to LOW transition of the input current pulse to the 1.5 V level on the LOW to HIGH transition of the output voltage pulse.

(6) tPHL– Propagation delay is measured from the 3.75mA level on the LOW to HIGH transition of the input current pulse to the 1.5 V level on the HIGH to LOW transition of the output voltage pulse.

(7) tr– Rise time is measured from the 90% to the 10% levels on the LOW to HIGH transition of the output pulse.

(8) tf– Fall time is measured from the 10% to the 90% levels on the HIGH to LOW transition of the output pulse.

(9) tELH– Enable input propagation delay is measured from the 1.5V level on the HIGH to LOW transition of the input voltage pulse to the 1.5V level on the LOW to HIGH transition of the output voltage pulse.

(10) tEHL– Enable input propagation delay is measured from the 1.5V level on the LOW to HIGH transition of the input voltage pulse to the 1.5V level on the HIGH to LOW transition of the output voltage pulse.

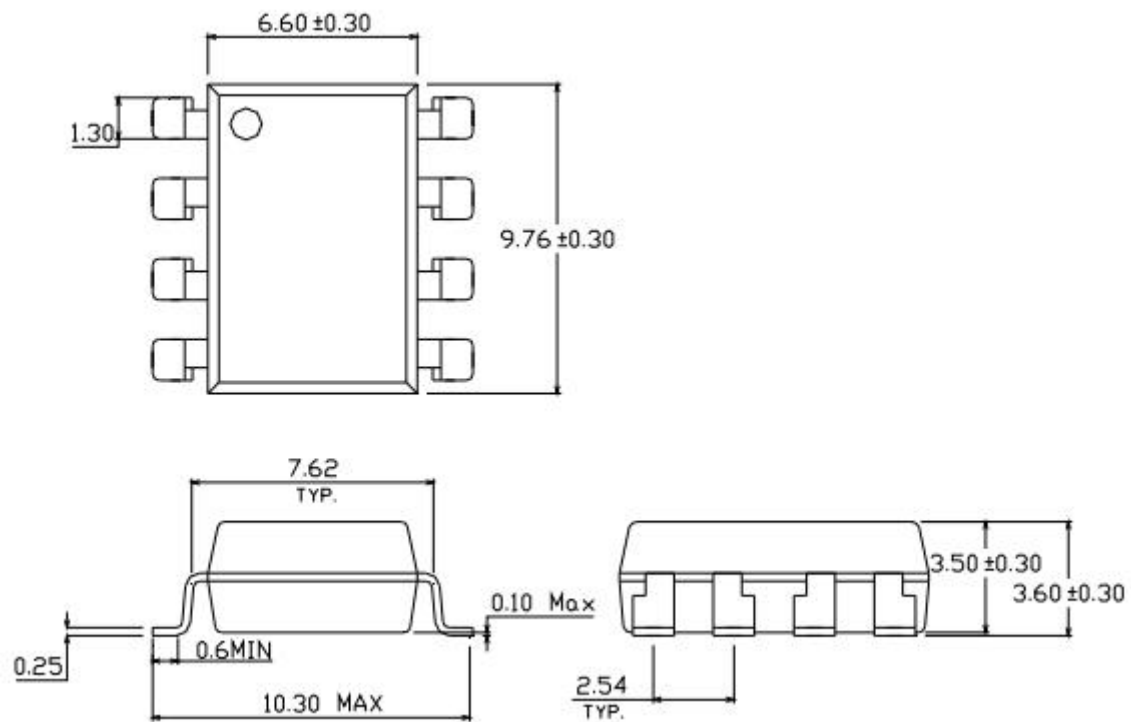
(11) CMH– The maximum tolerable rate of rise of the common mode voltage to ensure the output will remain in the HIGH state (i.e., $V_{OUT} > 2.0V$).

(12) CML– The maximum tolerable rate of rise of the common mode voltage to ensure the output will remain in the LOW output state (i.e., $V_{OUT} < 0.8V$).



Outline Dimension

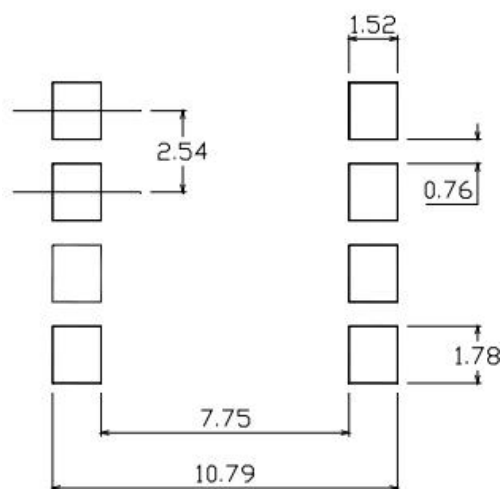
SMD-8



Unit: mm

Tolerance: ± 0.1 mm

Recommended solder pad Design



Unit: mm

Tolerance: ± 0.1 mm

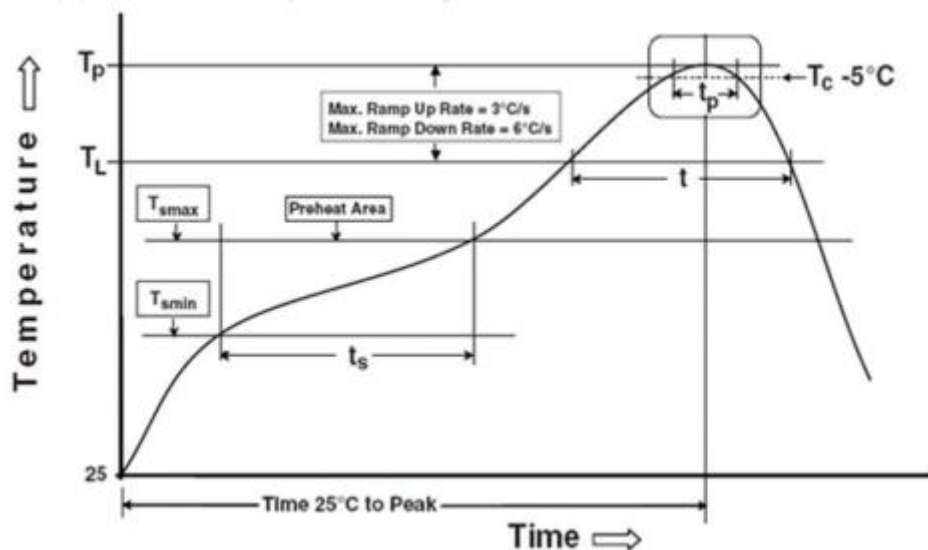


Temperature Profile Of Soldering

1. IR Reflow soldering

(IPC/JEDEC J-STD-020D compliant)

Profile item	Conditon
Preheat	
Temperature min (T _{smin})	150 °C
Temperature max (T _{smax})	200°C
Time (T _{smin} to T _{smax}) (t _s)	60-120 seconds 3 °C/ second max
Average ramp-up rate (T _{smax} to T _p)	
Other	
Liquidus Temperature (T _L)	217 °C
Time above Liquidus Temperature (t _L)	60-100 sec 260°C
Peak Temperature (T _p)	
Time within 5 °C of Actual Peak Temperature: T _p - 5°C	30 s
Ramp- Down Rate from Peak Temperature	6°C /second max.
Time 25°C to peak temperature	8 minutes max. 3 times
Reflow times	



Notes:

One time soldering reflow is recommended within the condition of temperature and time profile shown below. Do not solder more than three times.



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